

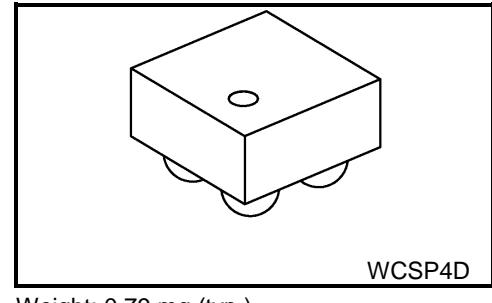
TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

TCK106AG, TCK107AG, TCK108AG

1.0 A Load Switch IC with Slew Rate Control Driver in Ultra Small Package

The TCK106AG, TCK107AG and TCK108AG are load switch ICs for a general power management with slew rate control driver, featuring low ON resistance and wide input voltage operation from 1.1 to 5.5 V. ON resistance is only 34 mΩ typical at 5.0 V, -0.5 A condition and output current is available on 1.0 A. TCK107AG and TCK108AG feature output auto-discharge function.

These devices are available in 0.4 mm pitch ultra small package W CSP4D (0.79 mm x 0.79 mm, t: 0.55 mm) . Thus this device is ideal for portable applications that require high-density board assembly such as cellular phone.

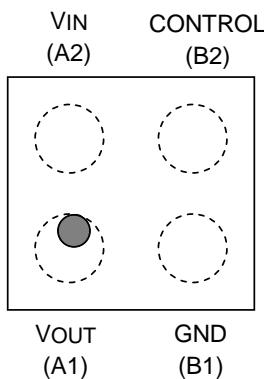


Weight: 0.79 mg (typ.)

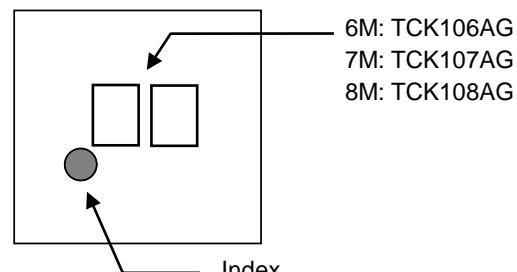
Feature

- Low ON resistance :
 - $R_{ON} = 34 \text{ m}\Omega$ (typ.) at $V_{IN} = 5.0 \text{ V}, -0.5 \text{ A}$
 - $R_{ON} = 42 \text{ m}\Omega$ (typ.) at $V_{IN} = 3.3 \text{ V}, -0.5 \text{ A}$
 - $R_{ON} = 71 \text{ m}\Omega$ (typ.) at $V_{IN} = 1.8 \text{ V}, -0.5 \text{ A}$
 - $R_{ON} = 139 \text{ m}\Omega$ (typ.) at $V_{IN} = 1.2 \text{ V}, -0.2 \text{ A}$
 - $R_{ON} = 176 \text{ m}\Omega$ (typ.) at $V_{IN} = 1.1 \text{ V}, -0.2 \text{ A}$
- Low Quiescent current
 - $I_Q = 110 \text{ nA}$ (typ.) at $V_{IN} = 5.5 \text{ V}, 0 \text{ mA}$
- High output current: $I_{OUT} = 1.0 \text{ A}$
- Wide input voltage operation: $V_{IN} = 1.1$ to 5.5 V
- Built in Slew rate control driver
- Built in Auto-discharge (TCK107AG and TCK108AG)
- Active High and Pull down connection between CONTROL and GND (TCK106AG and TCK107AG)
- Active Low (TCK108AG)
- Ultra small package : W CSP4D (0.79 mm x 0.79 mm, t: 0.55 mm)

Pin Assignment(Top view)



Top marking



Start of commercial production
2015-06

Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating		Unit
Input voltage	V _{IN}	-0.3 to 6.0		V
Control voltage	V _{CT}	-0.3 to 6.0		V
Output voltage	V _{OUT}	-0.3 to V _{IN} + 0.3		(Note 1) V
Output current	I _{OUT}	DC	1.0	A
Power dissipation	P _D		800	(Note 2) mW
Operating temperature range	T _{opr}		-40 to 85	°C
Junction temperature	T _j		150	°C
Storage temperature	T _{stg}		-55 to 150	°C

Note : Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

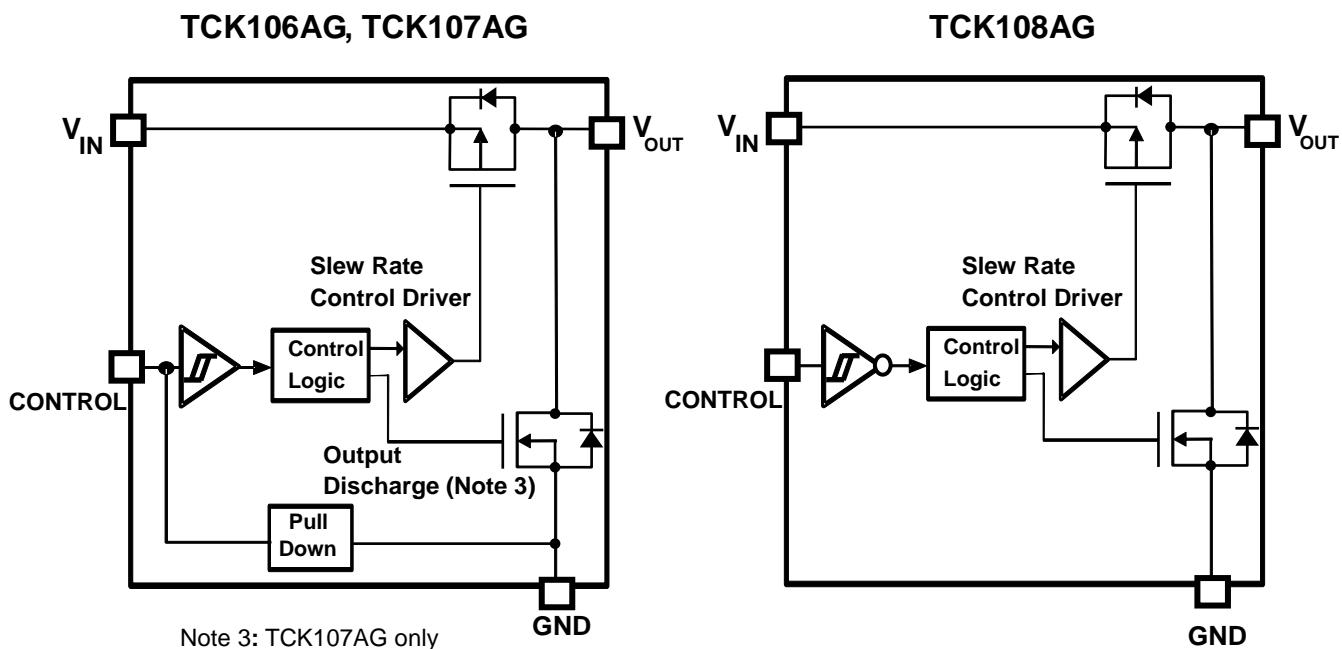
Note 1 : V_{IN} +0.3 ≤ 6.0 V

Note 2: Rating at mounting on a board

(Glass epoxy board dimension: 40 mm x 40 mm, both sides of board)

Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

Through hole: diameter 0.5 mm x 28

Block Diagram**Operating conditions**

Characteristics	Symbol	Condition	Min	Max	Unit
Input voltage	V _{IN}	—	1.1	5.5	V
Output current	I _{OUT}	—		1.0	A
CONTROL High-level input voltage	V _{IH}	1.1 V ≤ V _{IN} ≤ 5.5 V	0.9	—	V
CONTROL Low-level input voltage	V _{IL}		—	0.4	V

Electrical Characteristics**DC Characteristics (Ta = -40 to 85°C)**

Characteristics	Symbol	Test Condition		Min	Typ.	Max	Unit
Quiescent current (ON state)	I _Q	V _{IN} = V _{CT} = 5.5 V, I _{OUT} = 0 mA	TCK106AG TCK107AG	—	110	230	nA
		V _{IN} = 5.5 V, V _{CT} = 0 V, I _{OUT} = 0 mA	TCK108AG				
Standby current (OFF state)	I _{Q(OFF)}	V _{IN} = 5.5 V, V _{CT} = 0 V, V _{OUT} = OPEN (Note 4)	TCK106AG TCK107AG	—	65	150	nA
		V _{IN} = V _{CT} = 5.5 V, V _{OUT} = OPEN (Note 4)	TCK108AG				
Switch leakage current(OFF state)	I _{SD(OFF)}	V _{IN} = 5.5 V, V _{CT} = 0 V, V _{OUT} = GND	TCK106AG TCK107AG	—	14	1000	nA
		V _{IN} = V _{CT} = 5.5 V, V _{OUT} = GND	TCK108AG				
On resistance	R _{ON}	V _{IN} = 5.0 V, I _{OUT} = -0.5 A		—	34	55	mΩ
		V _{IN} = 3.3 V, I _{OUT} = -0.5 A		—	42	68	
		V _{IN} = 1.8 V, I _{OUT} = -0.5 A		—	71	105	
		V _{IN} = 1.2 V, I _{OUT} = -0.2 A		—	139	220	
		V _{IN} = 1.1 V, I _{OUT} = -0.2 A		—	176	—	
Discharge on resistance	R _{SD}	— (TCK107AG and TCK108AG)		—	100	—	Ω

Note 4: Except I_{SD(OFF)} OFF-state switch current

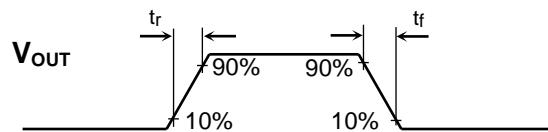
AC Characteristics ($T_a = 25^\circ C$) $V_{IN} = 1.2 V$

Characteristics	Symbol	Test Condition (Figure 1)		Min	Typ.	Max	Unit
V_{OUT} rise time	t_r	$R_L = 500 \Omega, C_L = 0.1 \mu F$		—	290	—	μs
V_{OUT} fall time	t_f	$R_L = 500 \Omega, C_L = 0.1 \mu F$	TCK107AG TCK108AG	—	30	—	μs
			TCK106AG	—	104	—	
Turn on delay	t_{ON}	$R_L = 500 \Omega, C_L = 0.1 \mu F$		—	305	—	μs
Turn off delay	t_{OFF}	$R_L = 500 \Omega, C_L = 0.1 \mu F$		—	5	—	μs

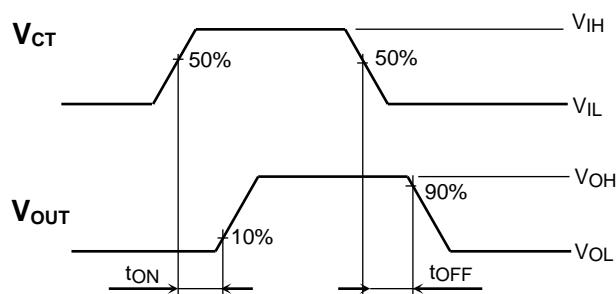
 $V_{IN} = 3.3 V$

Characteristics	Symbol	Test Condition (Figure 1)		Min	Typ.	Max	Unit
V_{OUT} rise time	t_r	$R_L = 500 \Omega, C_L = 0.1 \mu F$		—	130	—	μs
V_{OUT} fall time	t_f	$R_L = 500 \Omega, C_L = 0.1 \mu F$	TCK107AG TCK108AG	—	25	—	μs
			TCK106AG	—	110	—	
Turn on delay	t_{ON}	$R_L = 500 \Omega, C_L = 0.1 \mu F$		—	100	—	μs
Turn off delay	t_{OFF}	$R_L = 500 \Omega, C_L = 0.1 \mu F$		—	10	—	μs

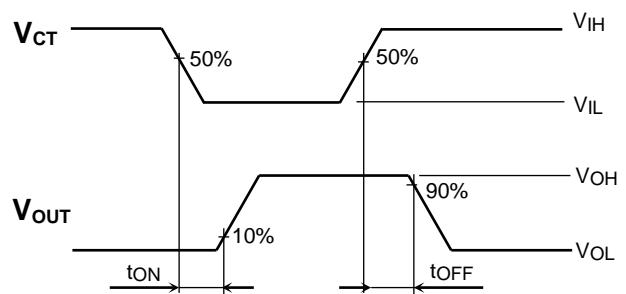
AC Waveform



TCK106AG, TCK107AG

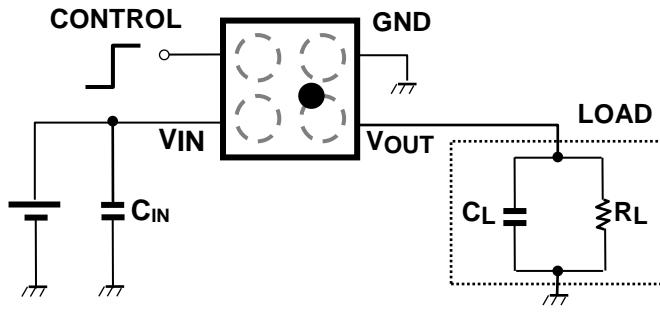


TCK108AG

Figure 1 $t_r, t_f, t_{ON}, t_{OFF}$ Waveforms

Application Note**1. Application circuit example (top view)**

The figure below shows configuration example for TCK106AG, TCK107AG and TCK108AG.



Part number	Control voltage	IC Operation
TCK106AG	HIGH	ON
TCK107AG	LOW	OFF
	OPEN	OFF
TCK108AG	HIGH	OFF
	LOW	ON

1) Input capacitor

An input capacitor (C_{IN}) is not necessary for the guaranteed operation of TCK106AG, TCK107AG and TCK108AG. However, the use of C_{IN} is effective to reduce voltage drop due to sharp changes in output current and also for improved stability of the power supply. When used, place C_{IN} as close to V_{IN} pin to improve stability of the power supply. Also, due to the C_{IN} selected, $V_{IN} < V_{OUT}$ may occur, causing a reverse current to flow through the body diode of the pass-through p-ch MOSFET of the load switch IC. In this case, a higher value for C_{IN} as compared to C_L is recommended.

2) Output capacitor

An output capacitor (C_{OUT}) is not necessary for the guaranteed operation of TCK106AG, TCK107AG and TCK108AG. However, there is a possibility of overshoot or undershoot caused by output load transient response, board layout and parasitic components of load switch IC. In this case, an output capacitor with C_{OUT} more than $0.1\mu F$ is recommended.

3) Control pin

A control pins for TCK106AG and TCK107AG are both Active High and TCK108AG is Active Low. These controls both the pass-through p-ch MOSFET and the discharge n-ch MOSFET (except TCK106AG), operated by the control voltage and Schmitt trigger. When the control voltage level is High (Low; TCK108AG), p-ch MOSFET is ON state and n-ch MOSFET is OFF state. When control voltage level is Low (High; TCK108AG), and the state of the MOSFETs is reversed. Also, pull down resistance equivalent to a few $M\Omega$ s is connected between CONTROL and GND, thus the load switch IC is in OFF state even when CONTROL pin is OPEN(except TCK108AG). In addition, CONTROL pin has a tolerant function such that it can be used even if the control voltage is higher than the input voltage.

2. Power Dissipation

Board-mounted power dissipation ratings for TCK106AG, TCK107AG and TCK108AG are available in the Absolute Maximum Ratings table

Power dissipation is measured on the board condition shown below.

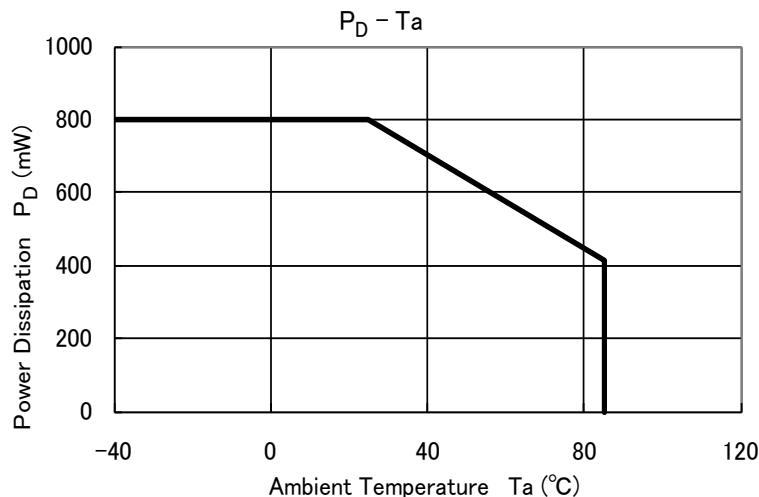
[The Board Condition]

Board material: Glass epoxy (FR4)

Board dimension: 40 mm x 40 mm (both sides of board), t=1.8 mm

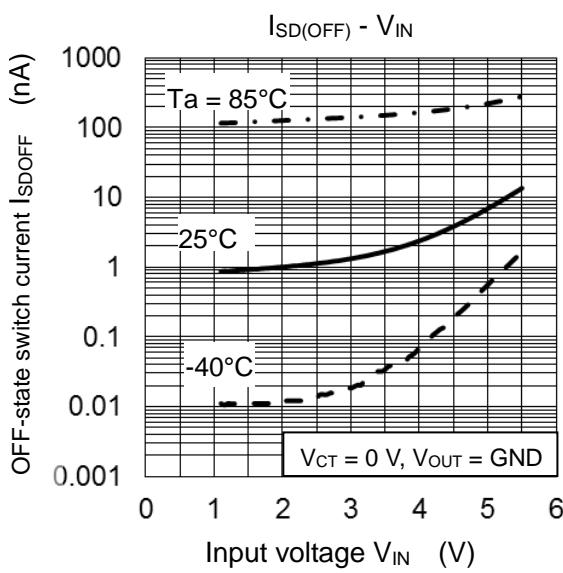
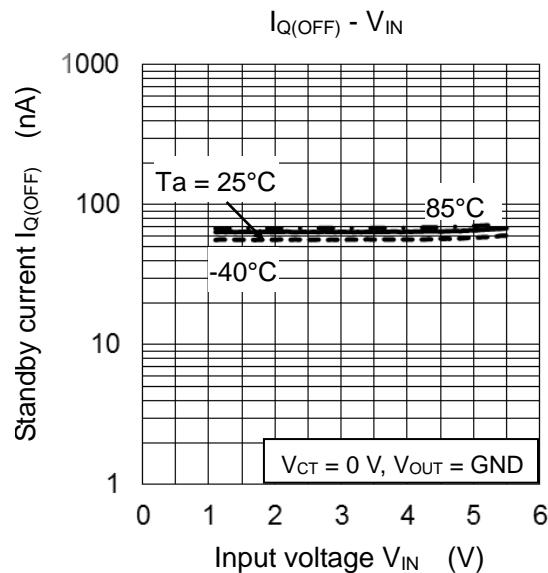
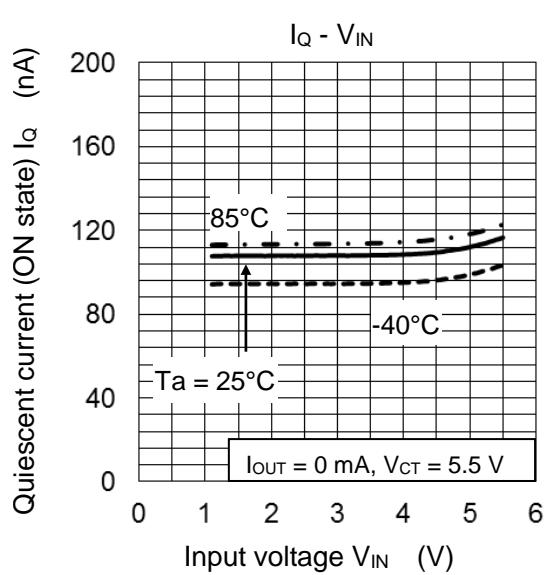
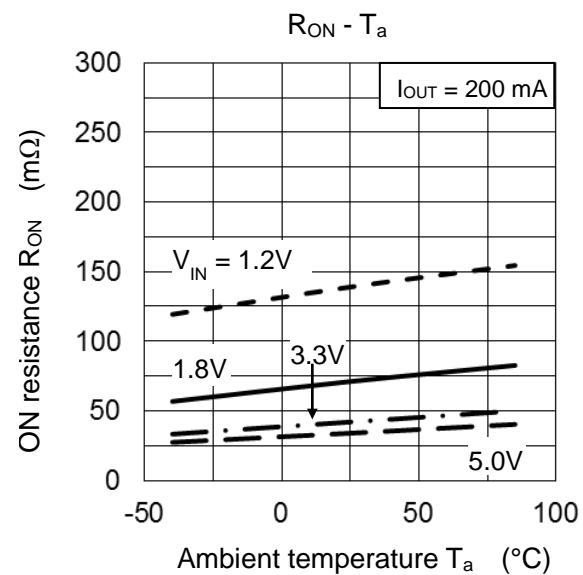
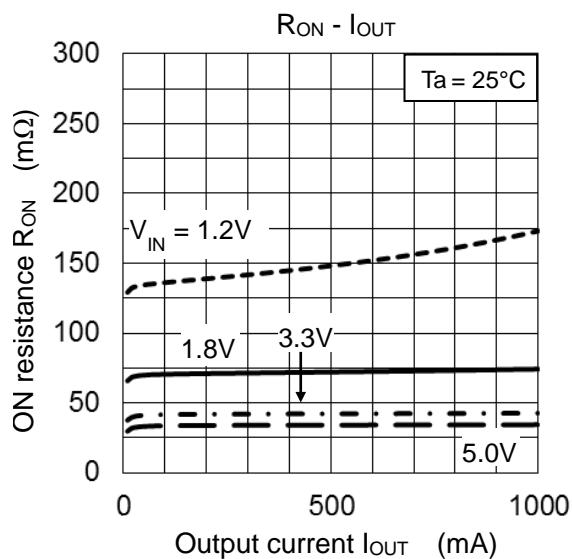
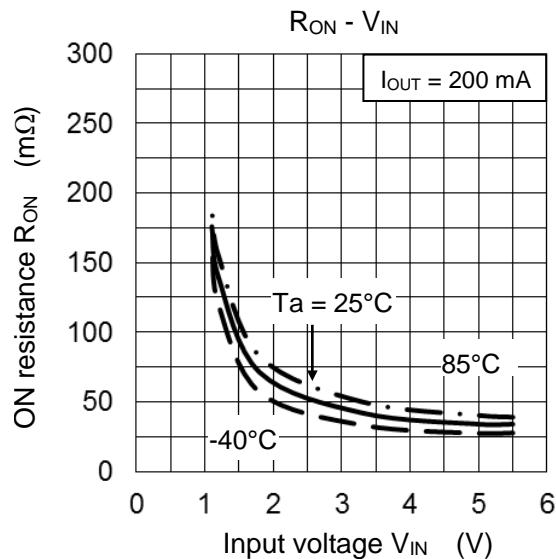
Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

Through hole: diameter 0.5 mm x 28

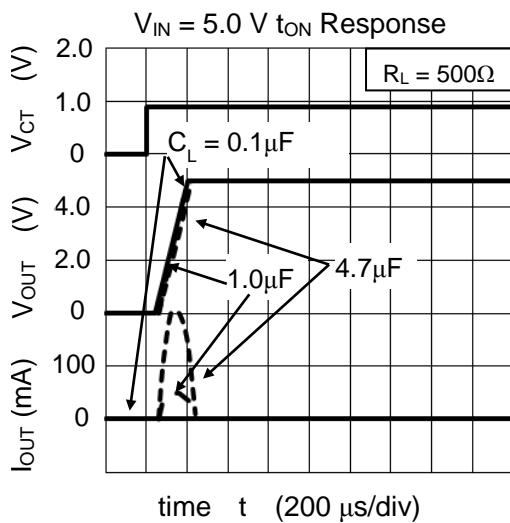
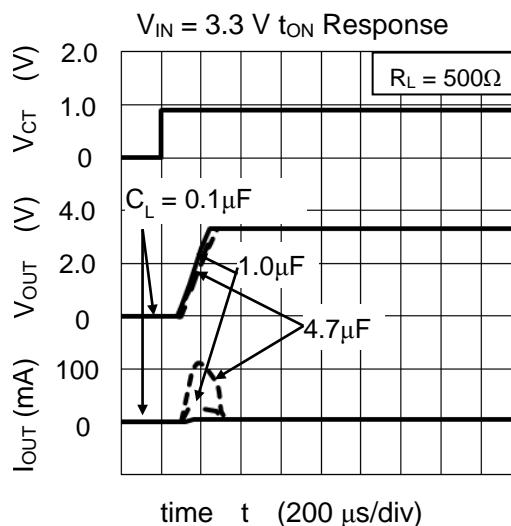
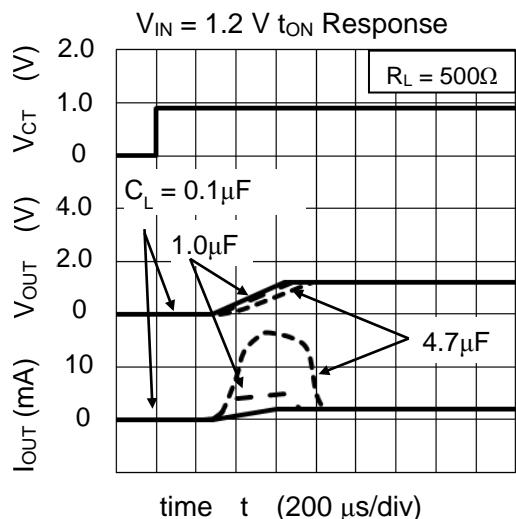


Please allow sufficient margin when designing a board pattern to fit the expected power dissipation. Also take into consideration the ambient temperature, input voltage, output current etc and applying the appropriate derating for allowable power dissipation during operation.

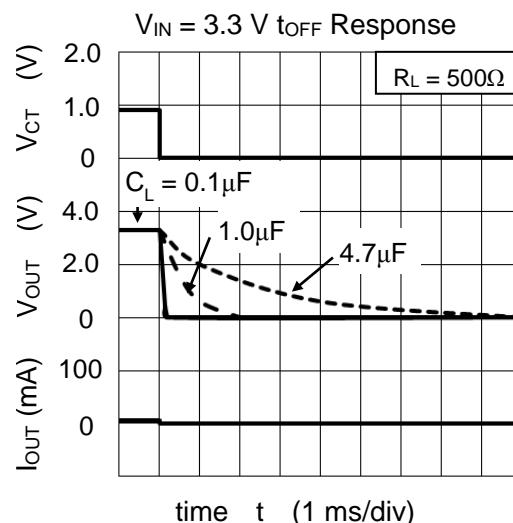
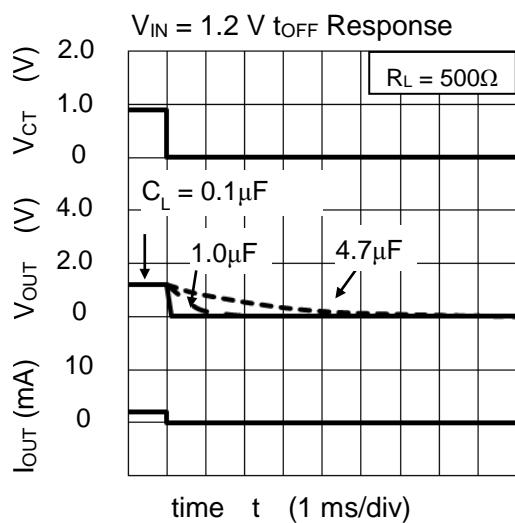
Representative Common Characteristics

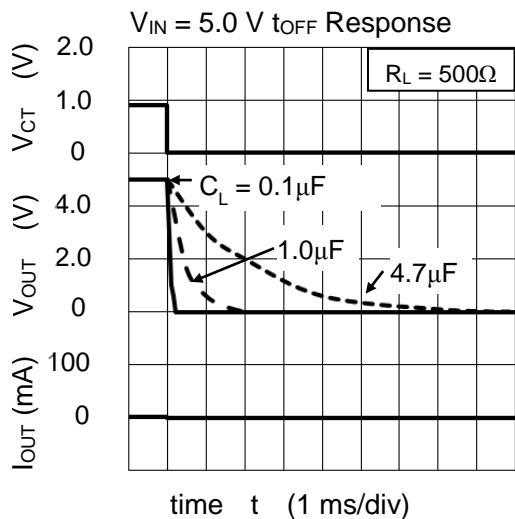
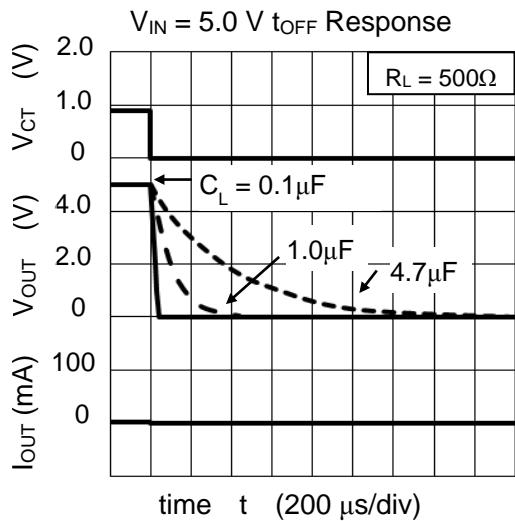
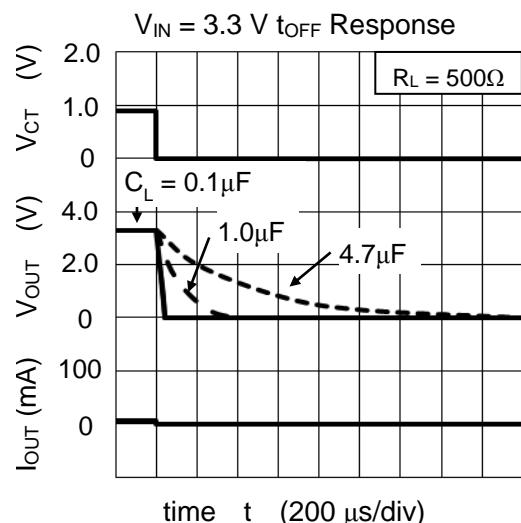
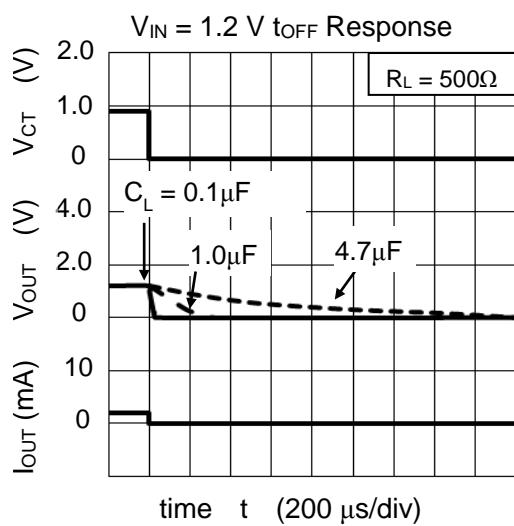


TCK107AG t_{ON} Response



TCK106AG t_{OFF} Response

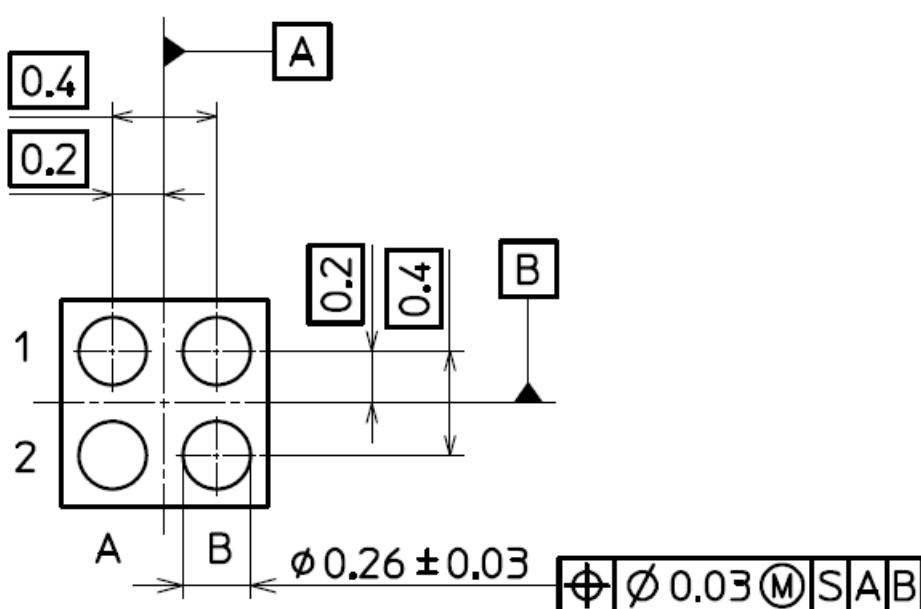
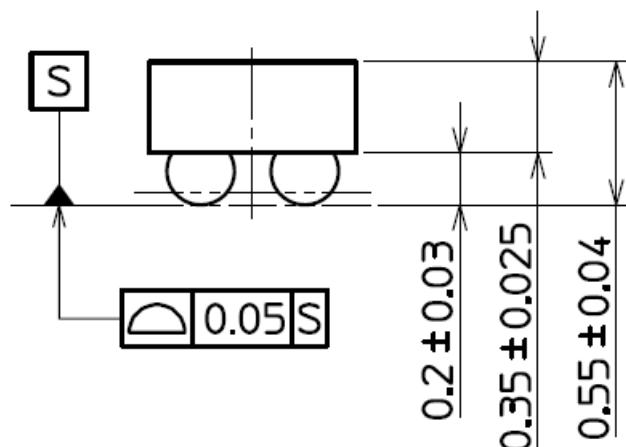
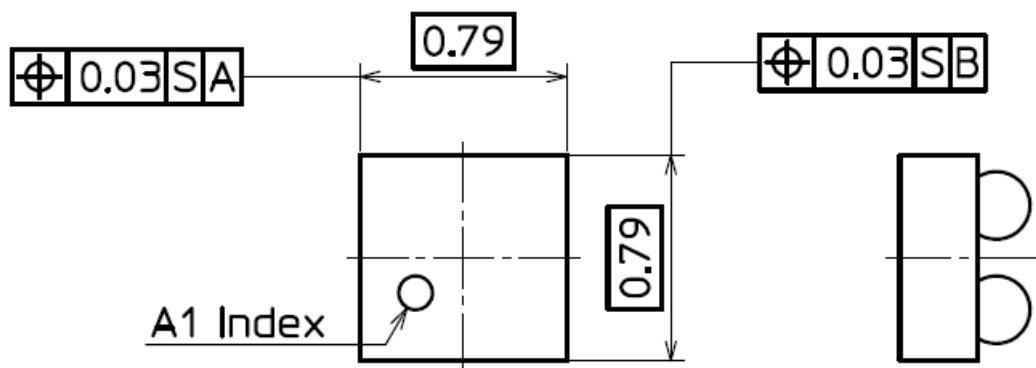


**TCK107AG t_{OFF} Response**

Package Dimensions

WCSP4D

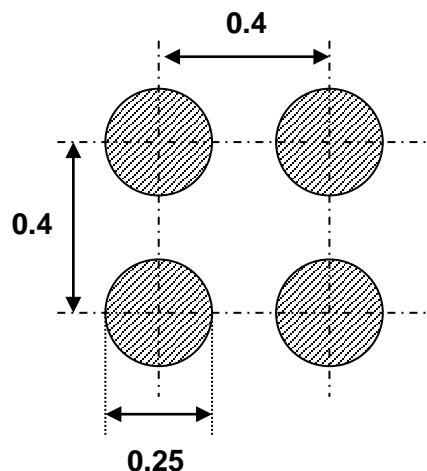
Unit: mm

**BOTTOM VIEW**

Weight : 0.79 mg (typ.)

Land pattern dimensions for reference only

Unit: mm



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